

FIELD INSPECTION REPORT Quality Control Form	ITP No.:	
	Inspection Gr.	
	Report No.	
	Date	

CHIPPING & PADDING INSPECTION FOR STRUCTURE

NO	Column No	Dimension	Condition		Elevation		Difference	Remarks
			Chip	Pad	Design	Actual		
1.								
2.								
3.								
4.								
5.								
6.								
7.								
8.								
9.								
10.								
11.								
12.								
13.								
14.								
15.								
16.								
17.								
18.								
19.								
20.								

SUBCON. QC	CONTRACTOR/TPI	COMPANY
DATE:	DATE:	DATE:

NOTE:

Legend ACC:ACCEPT NA.: Not Applicable REJ: REJECT